

(12) International Application Status Report

Received at International Bureau: 22 September 2018 (22.09.2018)

Information valid as of: 15 July 2019 (15.07.2019)

Report generated on: 20 October 2019 (20.10.2019)

(10) Publication number:

WO2019/046468

(43) Publication date:

07 March 2019 (07.03.2019)

(26) Publication language:

English (EN)

(21) Application Number:

PCT/US2018/048612

(22) Filing Date:

29 August 2018 (29.08.2018)

(25) Filing language:

English (EN)

(31) Priority number(s):

62/551,751 (US)

(31) Priority date(s):

29 August 2017 (29.08.2017)

(31) Priority status:

Priority document received (in compliance with PCT Rule 17.1)

(51) International Patent Classification:

B32B 27/00 (2006.01); **B32B 9/00** (2006.01); **B65D 73/02** (2006.01); **B65D 85/86** (2006.01); **C08K 5/01** (2006.01)

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(54) Title (EN): RIGID CARRIER ASSEMBLIES HAVING AN INTEGRATED ADHESIVE FILM

(54) Title (FR): ENSEMBLES SUPPORTS RIGIDES À FILM ADHÉSIF INTÉGRÉ

(57) Abstract:

(EN): Introduced here are carrier trays that include an adhesive film affixed to a deck area. For example, the adhesive film may be integrally laminated onto the top surface of the carrier tray as a single continuous (i.e., unbroken) sheet. The adhesive film may substantially conform to the top surface of the carrier tray. Semiconductor component(s) can be secured to the carrier tray based on the adhesiveness of the adhesive film. Said another way, proper securement of the semiconductor component(s) to the carrier tray may depend on the tackiness of the constituent material(s) of the adhesive film.

(FR): L'invention concerne des plateaux de support qui comprennent un film adhésif fixé à une zone supérieure. Par exemple, le film adhésif peut être stratifié d'un seul tenant sur la surface supérieure du plateau de support sous la forme d'une seule feuille continue (à savoir, ininterrompue). Le film adhésif peut se conformer sensiblement à la surface supérieure du plateau de support. Le ou les composants semi-conducteurs peuvent être fixés au plateau de support sur la base de l'adhésivité du film adhésif. En d'autres termes, une fixation appropriée du ou des composants semi-conducteurs au plateau de support peut dépendre de l'adhésivité du ou des matériaux constitutifs du film adhésif.

International search report:

Received at International Bureau: 13 January 2019 (13.01.2019) [US]

International Report on Patentability (IPRP) Chapter II of the PCT:

Not available

(81) Designated States:

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW

European Patent Office (EPO) : AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR

African Intellectual Property Organization (OAPI) : BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG

African Regional Intellectual Property Organization (ARIPO) : BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW

Eurasian Patent Organization (EAPO) : AM, AZ, BY, KG, KZ, RU, TJ, TM